

Features

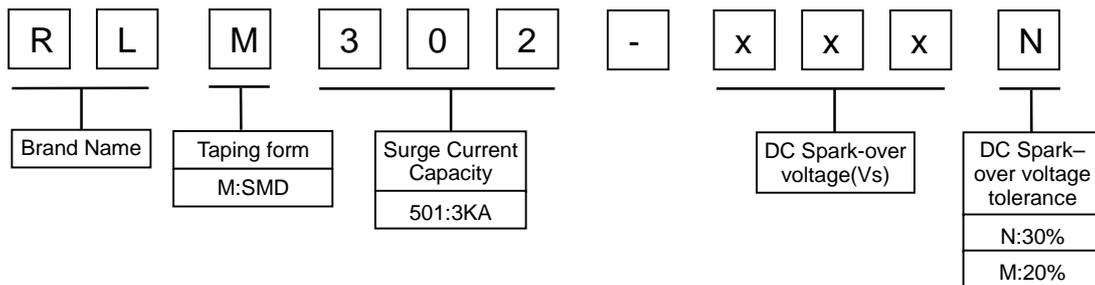
- I RoHS compliant.
- I Bilateral symmetrical.
- I Less decay at on/off state.
- I Approximately zero leaking current before clamping voltage
- I High capability to withstand repeated lightning strikes.
- I Low electrode capacitance($\leq 1.0\text{pF}$) and high isolation ($\geq 100\text{M}\Omega$).
- I Temperature, humidity and lightness insensitive.
- I Working temperature range: : $-45^{\circ}\text{C} \sim +85^{\circ}\text{C}$
- I Storing temperature range: $-45^{\circ}\text{C} \sim +85^{\circ}\text{C}$



Applications

- I Power Supplies
- I Motor sparks eliminating
- I Relay switching spark absorbing
- I Data line pulse guarding
- I Telephone/Fax/Modem
- I High frequency signal transmitters/receivers
- I Satellite antenna
- I Radio amplifiers
- I Alarm systems
- I Cathode ray tubes in Monitors/Television Viewing Systems

Part Number Code

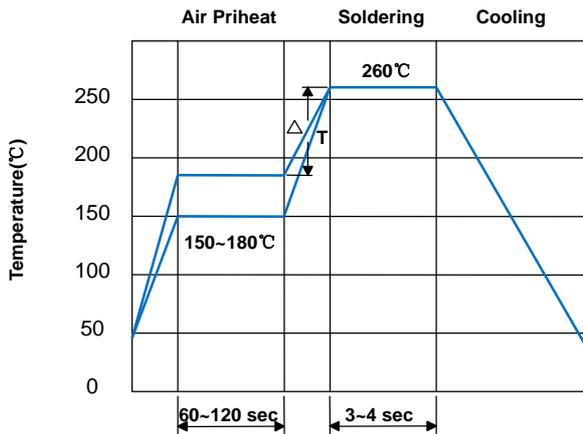


Electrical Characteristics

Type Number	DC Spark-Over Voltage	Min. Insulation Resistance		Max. Capacitance (1kHz-6Vmax.)	Surge Current Capacity	Surge Life Test
	Vs	Test Voltage	I _R	Cj	8/20μs	
	V	V	MΩ	pF	A	
RLM302-141N	140±30%	50	100	1	3000	1kHz-10KV Max (10X700 μ sec-6000V 150A 10 time)
RLM302-181N	180±30%	50	100	1	3000	
RLM302-201M	200±20%	100	100	1	3000	
RLM302-301M	300±20%	100	100	1	3000	
RLM302-401M	400±20%	250	100	1	3000	
RLM302-501M	500±20%	250	100	1	3000	

Recommended Soldering Conditions

Flow Soldering Conditions



Hand Soldering

Solder iron temperature: 350±5°C
Heating time: 3 seconds max.

General attention to soldering

- 1.High soldering temperatures and long soldering times can cause leaching of the termination, decrease in adherence strength, and the change of characteristic may occur.
- 2.For soldering, please refer to the soldering curves above. However, please keep exposures to temperatures exceeding 200°C to fewer than 50 seconds.
- 3.Please use a mild flux (containing less than 0.2wt% Cl). Also, if the flux is water soluble, be sure to wash thoroughly to remove any residue from the underside of components that could affect resistance.

- 1) Time shown in the above figures is measured from the point when chip surface reaches temperature.
- 2) Temperature difference in high temperature part should be within 110°C
- 3) After soldering, do not force cool, allow the parts to cool gradually.

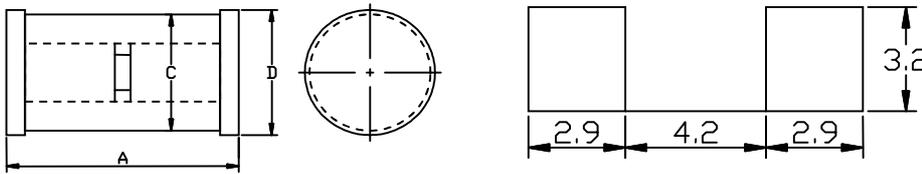
Cleaning

When using ultrasonic cleaning, the board may resonate if the output power is too high. Since this vibration can cause cracking or a decrease in the adherence of the termination, we recommend that you use the conditions below.

- Frequency: 40kHz max.
- Output power: 20W/liter
- Cleaning time: 5 minutes max.

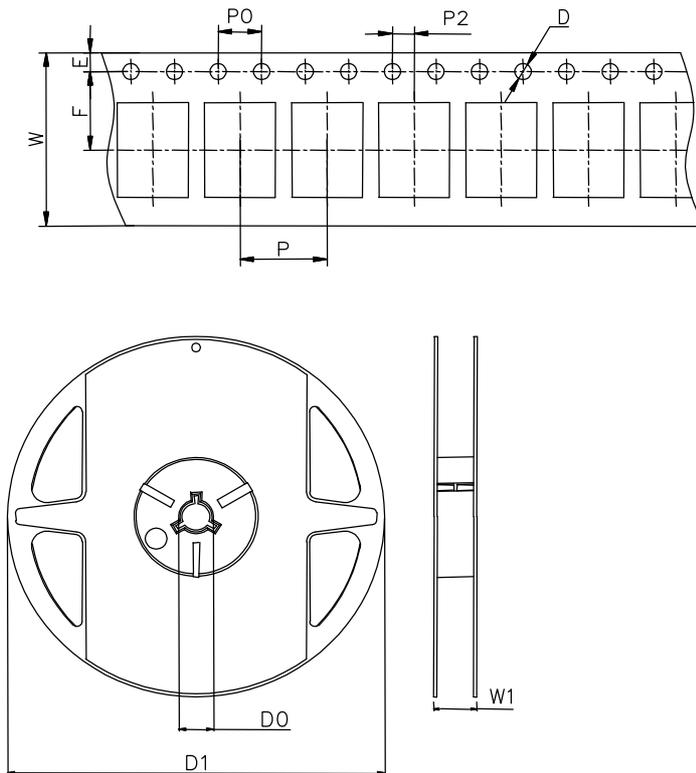


Dimensions & Recommended Pad Size(mm)



DIM	Millimeters	Inches
A	6.0±0.5	0.236±0.02
C	Φ3.1±0.5	0.122±0.02
D	Φ3.3±0.5	0.13±0.02

Taping and Reel Specifications



Symbol	Millimeters	Inches
W	16±0.2	0.630±0.008
P	8±0.1	0.314±0.004
F	7.5±0.05	0.295±0.002
E	1.75±0.1	0.069±0.004
D	1.5±0.1	0.059±0.004
P0	4±0.1	0.157±0.004
P2	2±0.1	0.079±0.004
D0	13±0.15	0.512±0.006
D1	330±2	12.992±0.079
W1	20±0.2	0.787±0.008

Quantity:2000PCS Per Reel

